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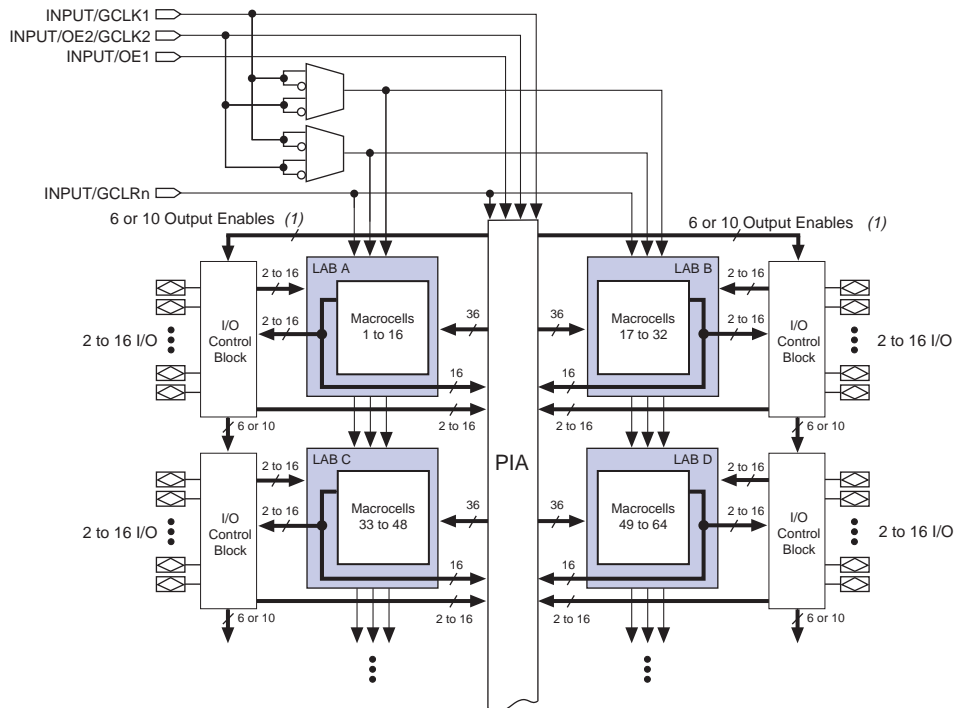
### Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

### Applications of Embedded - CPLDs

#### Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	5.5 ns
Voltage Supply - Internal	2.375V ~ 2.625V
Number of Logic Elements/Blocks	32
Number of Macrocells	512
Number of Gates	10000
Number of I/O	141
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	169-LFBGA
Supplier Device Package	169-UBGA (11x11)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/epm7512buc169-5">https://www.e-xfl.com/product-detail/intel/epm7512buc169-5</a>

**Figure 1. MAX 7000B Device Block Diagram****Note:**

- (1) EPM7032B, EPM7064B, EPM7128B, and EPM7256B devices have six output enables. EPM7512B devices have ten output enables.

## Logic Array Blocks

The MAX 7000B device architecture is based on the linking of high-performance LABs. LABs consist of 16 macrocell arrays, as shown in Figure 1. Multiple LABs are linked together via the PIA, a global bus that is fed by all dedicated input pins, I/O pins, and macrocells.

Each LAB is fed by the following signals:

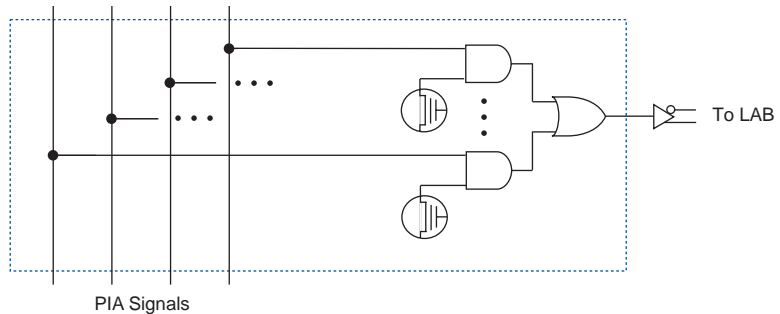
- 36 signals from the PIA that are used for general logic inputs
- Global controls that are used for secondary register functions
- Direct input paths from I/O pins to the registers that are used for fast setup times

### *Parallel Expanders*

Parallel expanders are unused product terms that can be allocated to a neighboring macrocell to implement fast, complex logic functions. Parallel expanders allow up to 20 product terms to directly feed the macrocell OR logic, with five product terms provided by the macrocell and 15 parallel expanders provided by neighboring macrocells in the LAB.

The Altera Compiler can automatically allocate up to three sets of up to five parallel expanders to the macrocells that require additional product terms. Each set of five parallel expanders incurs a small, incremental timing delay ( $t_{PEXP}$ ). For example, if a macrocell requires 14 product terms, the Compiler uses the five dedicated product terms within the macrocell and allocates two sets of parallel expanders; the first set includes five product terms and the second set includes four product terms, increasing the total delay by  $2 \times t_{PEXP}$ .

Two groups of eight macrocells within each LAB (e.g., macrocells 1 through 8, and 9 through 16) form two chains to lend or borrow parallel expanders. A macrocell borrows parallel expanders from lower-numbered macrocells. For example, macrocell 8 can borrow parallel expanders from macrocell 7, from macrocells 7 and 6, or from macrocells 7, 6, and 5. Within each group of eight, the lowest-numbered macrocell can only lend parallel expanders and the highest-numbered macrocell can only borrow them. [Figure 4](#) shows how parallel expanders can be borrowed from a neighboring macrocell.

**Figure 5. MAX 7000B PIA Routing**

While the routing delays of channel-based routing schemes in masked or field-programmable gate arrays (FPGAs) are cumulative, variable, and path-dependent, the MAX 7000B PIA has a predictable delay. The PIA makes a design's timing performance easy to predict.

### I/O Control Blocks

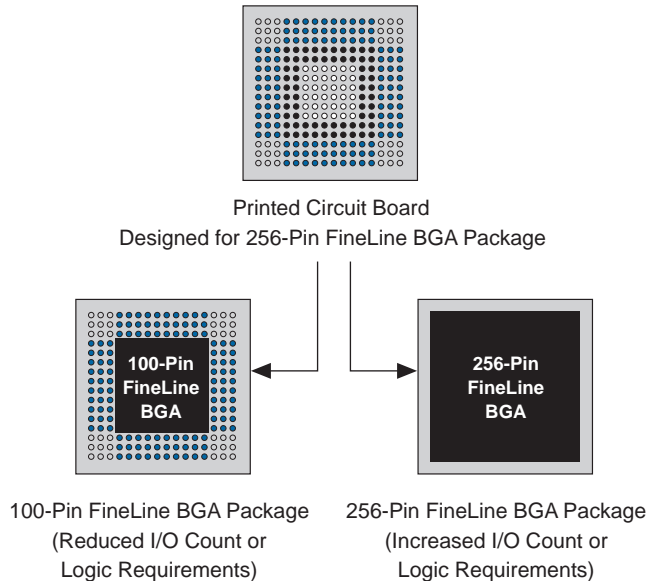
The I/O control block allows each I/O pin to be individually configured for input, output, or bidirectional operation. All I/O pins have a tri-state buffer that is individually controlled by one of the global output enable signals or directly connected to ground or  $V_{CC}$ . Figure 6 shows the I/O control block for MAX 7000B devices. The I/O control block has six or ten global output enable signals that are driven by the true or complement of two output enable signals, a subset of the I/O pins, or a subset of the I/O macrocells.

## SameFrame Pin-Outs

MAX 7000B devices support the SameFrame pin-out feature for FineLine BGA and 0.8-mm Ultra FineLine BGA packages. The SameFrame pin-out feature is the arrangement of balls on FineLine BGA and 0.8-mm Ultra FineLine BGA packages such that the lower-ball-count packages form a subset of the higher-ball-count packages. SameFrame pin-outs provide the flexibility to migrate not only from device to device within the same package, but also from one package to another. FineLine BGA packages are compatible with other FineLine BGA packages, and 0.8-mm Ultra FineLine BGA packages are compatible with other 0.8-mm Ultra FineLine BGA packages. A given printed circuit board (PCB) layout can support multiple device density / package combinations. For example, a single board layout can support a range of devices from an EPM7064B device in a 100-pin FineLine BGA package to an EPM7512B device in a 256-pin FineLine BGA package.

The Altera software provides support to design PCBs with SameFrame pin-out devices. Devices can be defined for present and future use. The Altera software generates pin-outs describing how to layout a board to take advantage of this migration (see [Figure 7](#)).

**Figure 7. SameFrame Pin-Out Example**



The instruction register length of MAX 7000B devices is ten bits. The MAX 7000B USERCODE register length is 32 bits. [Tables 7 and 8](#) show the boundary-scan register length and device IDCODE information for MAX 7000B devices.

**Table 7. MAX 7000B Boundary-Scan Register Length**

Device	Boundary-Scan Register Length
EPM7032B	96
EPM7064B	192
EPM7128B	288
EPM7256B	480
EPM7512B	624

**Table 8. 32-Bit MAX 7000B Device IDCODE** *Note (1)*

Device	IDCODE (32 Bits)			
	Version (4 Bits)	Part Number (16 Bits)	Manufacturer's Identity (11 Bits)	1 (1 Bit) (2)
EPM7032B	0010	0111 0000 0011 0010	00001101110	1
EPM7064B	0010	0111 0000 0110 0100	00001101110	1
EPM7128B	0010	0111 0001 0010 1000	00001101110	1
EPM7256B	0010	0111 0010 0101 0110	00001101110	1
EPM7512B	0010	0111 0101 0001 0010	00001101110	1

**Notes:**

- (1) The most significant bit (MSB) is on the left.
- (2) The least significant bit (LSB) for all JTAG IDCODEs is 1.



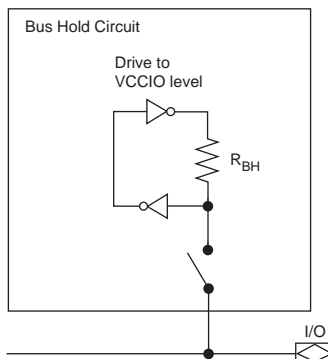
See [Application Note 39 \(IEEE 1149.1 \(JTAG\) Boundary-Scan Testing in Altera Devices\)](#) for more information on JTAG boundary-scan testing.

[Figure 8](#) shows the timing information for the JTAG signals.

Two inverters implement the bus-hold circuitry in a loop that weakly drives back to the I/O pin in user mode.

Figure 10 shows a block diagram of the bus-hold circuit.

**Figure 10. Bus-Hold Circuit**



## PCI Compatibility

MAX 7000B devices are compatible with PCI applications as well as all 3.3-V electrical specifications in the *PCI Local Bus Specification Revision 2.2* except for the clamp diode. While having multiple clamp diodes on a signal trace may be redundant, designers can add an external clamp diode to meet the specification. Table 13 shows the MAX 7000B device speed grades that meet the PCI timing specifications.

**Table 13. MAX 7000B Device Speed Grades that Meet PCI Timing Specifications**

Device	Specification	
	33-MHz PCI	66-MHz PCI
EPM7032B	All speed grades	-3
EPM7064B	All speed grades	-3
EPM7128B	All speed grades	-4
EPM7256B	All speed grades	-5 (1)
EPM7512B	All speed grades	-5 (1)

**Note:**

- (1) The EPM7256B and EPM7512B devices in a -5 speed grade meet all PCI timing specifications for 66-MHz operation except the Input Setup Time to CLK—Bused Signal parameter. However, these devices are within 1 ns of that parameter. EPM7256B and EPM7512B devices meet all other 66-MHz PCI timing specifications.

**Table 16. MAX 7000B Device DC Operating Conditions** *Note (4)*

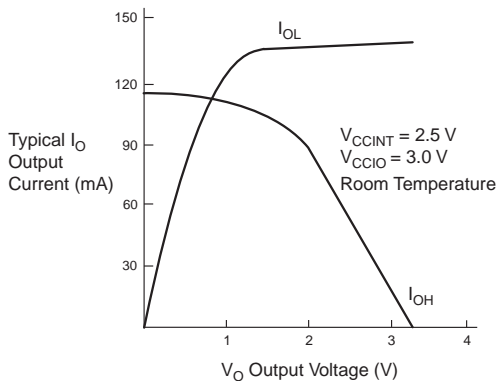
Symbol	Parameter	Conditions	Min	Max	Unit
$V_{IH}$	High-level input voltage for 3.3-V TTL/CMOS		2.0	3.9	V
	High-level input voltage for 2.5-V TTL/CMOS		1.7	3.9	V
	High-level input voltage for 1.8-V TTL/CMOS		$0.65 \times V_{CCIO}$	3.9	V
$V_{IL}$	Low-level input voltage for 3.3-V TTL/CMOS and PCI compliance		-0.5	0.8	V
	Low-level input voltage for 2.5-V TTL/CMOS		-0.5	0.7	V
	Low-level input voltage for 1.8-V TTL/CMOS		-0.5	$0.35 \times V_{CCIO}$	
$V_{OH}$	3.3-V high-level TTL output voltage	$I_{OH} = -8 \text{ mA DC}$ , $V_{CCIO} = 3.00 \text{ V}$ (5)	2.4		V
	3.3-V high-level CMOS output voltage	$I_{OH} = -0.1 \text{ mA DC}$ , $V_{CCIO} = 3.00 \text{ V}$ (5)	$V_{CCIO} - 0.2$		V
	2.5-V high-level output voltage	$I_{OH} = -100 \text{ } \mu\text{A DC}$ , $V_{CCIO} = 2.30 \text{ V}$ (5)	2.1		V
		$I_{OH} = -1 \text{ mA DC}$ , $V_{CCIO} = 2.30 \text{ V}$ (5)	2.0		V
		$I_{OH} = -2 \text{ mA DC}$ , $V_{CCIO} = 2.30 \text{ V}$ (5)	1.7		V
	1.8-V high-level output voltage	$I_{OH} = -2 \text{ mA DC}$ , $V_{CCIO} = 1.65 \text{ V}$ (5)	1.2		V
$V_{OL}$	3.3-V low-level TTL output voltage	$I_{OL} = 8 \text{ mA DC}$ , $V_{CCIO} = 3.00 \text{ V}$ (6)		0.4	V
	3.3-V low-level CMOS output voltage	$I_{OL} = 0.1 \text{ mA DC}$ , $V_{CCIO} = 3.00 \text{ V}$ (6)		0.2	V
	2.5-V low-level output voltage	$I_{OL} = 100 \text{ } \mu\text{A DC}$ , $V_{CCIO} = 2.30 \text{ V}$ (6)		0.2	V
		$I_{OL} = 1 \text{ mA DC}$ , $V_{CCIO} = 2.30 \text{ V}$ (6)		0.4	V
		$I_{OL} = 2 \text{ mA DC}$ , $V_{CCIO} = 2.30 \text{ V}$ (6)		0.7	V
	1.8-V low-level output voltage	$I_{OL} = 2 \text{ mA DC}$ , $V_{CCIO} = 1.7 \text{ V}$ (6)		0.4	V
$I_I$	Input leakage current	$V_I = -0.5 \text{ to } 3.9 \text{ V}$ (7)	-10	10	$\mu\text{A}$
$I_{OZ}$	Tri-state output off-state current	$V_I = -0.5 \text{ to } 3.9 \text{ V}$ (7)	-10	10	$\mu\text{A}$
$R_{ISP}$	Value of I/O pin pull-up resistor during in-system programming or during power up	$V_{CCIO} = 1.7 \text{ to } 3.6 \text{ V}$ (8)	20	74	$k\Omega$



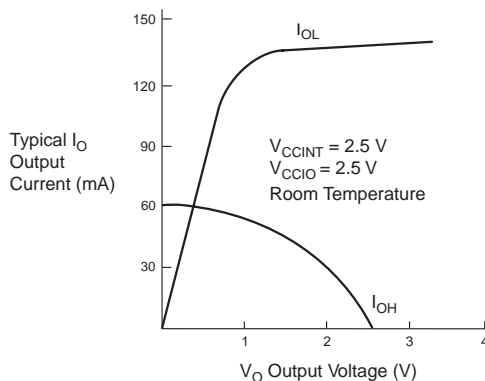
Figure 12 shows the typical output drive characteristics of MAX 7000B devices.

**Figure 12. Output Drive Characteristics of MAX 7000B Devices**

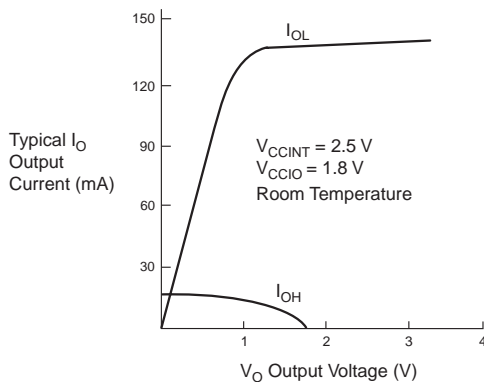
**3.3-V VCCIO**



**2.5-V VCCIO**



**1.8-V VCCIO**



**Table 20. EPM7032B Selectable I/O Standard Timing Adder Delays** *Notes (1)*

I/O Standard	Parameter	Speed Grade						Unit
		-3.5		-5.0		-7.5		
		Min	Max	Min	Max	Min	Max	
PCI	Input to PIA		0.0		0.0		0.0	ns
	Input to global clock and clear		0.0		0.0		0.0	ns
	Input to fast input register		0.0		0.0		0.0	ns
	All outputs		0.0		0.0		0.0	ns

**Notes to tables:**

- (1) These values are specified under the Recommended Operating Conditions in [Table 15 on page 29](#). See [Figure 14](#) for more information on switching waveforms.
- (2) These values are specified for a PIA fan-out of all LABs.
- (3) Measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (4) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{ACL}$ ,  $t_{CPW}$ ,  $t_{EN}$ , and  $t_{SEXP}$  parameters for macrocells running in low-power mode.

**Table 23. EPM7064B Selectable I/O Standard Timing Adder Delays (Part 1 of 2)** *Note (1)*

I/O Standard	Parameter	Speed Grade						Unit
		-3		-5		-7		
		Min	Max	Min	Max	Min	Max	
3.3 V TTL/CMOS	Input to PIA		0.0		0.0		0.0	ns
	Input to global clock and clear		0.0		0.0		0.0	ns
	Input to fast input register		0.0		0.0		0.0	ns
	All outputs		0.0		0.0		0.0	ns
2.5 V TTL/CMOS	Input to PIA		0.3		0.4		0.6	ns
	Input to global clock and clear		0.3		0.4		0.6	ns
	Input to fast input register		0.2		0.3		0.4	ns
	All outputs		0.2		0.3		0.4	ns
1.8 V TTL/CMOS	Input to PIA		0.5		0.7		1.1	ns
	Input to global clock and clear		0.5		0.7		1.1	ns
	Input to fast input register		0.4		0.6		0.9	ns
	All outputs		1.2		1.7		2.6	ns
SSTL-2 Class I	Input to PIA		1.3		1.9		2.8	ns
	Input to global clock and clear		1.2		1.7		2.6	ns
	Input to fast input register		0.9		1.3		1.9	ns
	All outputs		0.0		0.0		0.0	ns
SSTL-2 Class II	Input to PIA		1.3		1.9		2.8	ns
	Input to global clock and clear		1.2		1.7		2.6	ns
	Input to fast input register		0.9		1.3		1.9	ns
	All outputs		−0.1		−0.1		−0.2	ns
SSTL-3 Class I	Input to PIA		1.2		1.7		2.6	ns
	Input to global clock and clear		0.9		1.3		1.9	ns
	Input to fast input register		0.8		1.1		1.7	ns
	All outputs		0.0		0.0		0.0	ns
SSTL-3 Class II	Input to PIA		1.2		1.7		2.6	ns
	Input to global clock and clear		0.9		1.3		1.9	ns
	Input to fast input register		0.8		1.1		1.7	ns
	All outputs		0.0		0.0		0.0	ns
GTL+	Input to PIA		1.6		2.3		3.4	ns
	Input to global clock and clear		1.6		2.3		3.4	ns
	Input to fast input register		1.5		2.1		3.2	ns
	All outputs		0.0		0.0		0.0	ns

**Table 25. EPM7128B Internal Timing Parameters** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-4		-7		-10		
			Min	Max	Min	Max	Min	Max	
$t_{IN}$	Input pad and buffer delay			0.3		0.6		0.8	ns
$t_{IO}$	I/O input pad and buffer delay			0.3		0.6		0.8	ns
$t_{FIN}$	Fast input delay			1.3		2.9		3.7	ns
$t_{FIND}$	Programmable delay adder for fast input			1.0		1.5		1.5	ns
$t_{SEXP}$	Shared expander delay			1.5		2.8		3.8	ns
$t_{PEXP}$	Parallel expander delay			0.4		0.8		1.0	ns
$t_{LAD}$	Logic array delay			1.6		2.9		3.8	ns
$t_{LAC}$	Logic control array delay			1.4		2.6		3.4	ns
$t_{IOE}$	Internal output enable delay			0.1		0.3		0.4	ns
$t_{OD1}$	Output buffer and pad delay slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$		0.9		1.7		2.2	ns
$t_{OD3}$	Output buffer and pad delay slow slew rate = on $V_{CCIO} = 2.5\text{ V}$ or $3.3\text{ V}$	$C1 = 35\text{ pF}$		5.9		6.7		7.2	ns
$t_{ZX1}$	Output buffer enable delay slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$		1.8		3.3		4.4	ns
$t_{ZX3}$	Output buffer enable delay slow slew rate = on $V_{CCIO} = 2.5\text{ V}$ or $3.3\text{ V}$	$C1 = 35\text{ pF}$		6.8		8.3		9.4	ns
$t_{XZ}$	Output buffer disable delay	$C1 = 5\text{ pF}$		1.8		3.3		4.4	ns
$t_{SU}$	Register setup time		1.0		1.9		2.6		ns
$t_H$	Register hold time		0.4		0.8		1.1		ns
$t_{FSU}$	Register setup time of fast input		0.8		0.9		0.9		ns
$t_{FH}$	Register hold time of fast input		1.2		1.6		1.6		ns
$t_{RD}$	Register delay			0.5		1.1		1.4	ns
$t_{COMB}$	Combinatorial delay			0.2		0.3		0.4	ns
$t_{IC}$	Array clock delay			1.4		2.8		3.6	ns
$t_{EN}$	Register enable time			1.4		2.6		3.4	ns
$t_{GLOB}$	Global control delay			1.1		2.3		3.1	ns
$t_{PRE}$	Register preset time			1.0		1.9		2.6	ns
$t_{CLR}$	Register clear time			1.0		1.9		2.6	ns
$t_{PIA}$	PIA delay	(2)		1.0		2.0		2.8	ns
$t_{LPA}$	Low-power adder	(4)		1.5		2.8		3.8	ns

**Table 26. EPM7128B Selectable I/O Standard Timing Adder Delays (Part 2 of 2)** *Note (1)*

I/O Standard	Parameter	Speed Grade						Unit
		-4		-7		-10		
		Min	Max	Min	Max	Min	Max	
PCI	Input to PIA		0.0		0.0		0.0	ns
	Input to global clock and clear		0.0		0.0		0.0	ns
	Input to fast input register		0.0		0.0		0.0	ns
	All outputs		0.0		0.0		0.0	ns

**Notes to tables:**

- (1) These values are specified under the Recommended Operating Conditions in Table 15 on page 29. See Figure 14 for more information on switching waveforms.
- (2) These values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (3) Measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (4) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{ACL}$ ,  $t_{CPW}$ ,  $t_{EN}$ , and  $t_{SEXP}$  parameters for macrocells running in low-power mode.

**Table 29. EPM7256B Selectable I/O Standard Timing Adder Delays (Part 2 of 2)** *Note (1)*

I/O Standard	Parameter	Speed Grade						Unit
		-5		-7		-10		
		Min	Max	Min	Max	Min	Max	
PCI	Input to PIA		0.0		0.0		0.0	ns
	Input to global clock and clear		0.0		0.0		0.0	ns
	Input to fast input register		0.0		0.0		0.0	ns
	All outputs		0.0		0.0		0.0	ns

**Notes to tables:**

- (1) These values are specified under the Recommended Operating Conditions in Table 15 on page 29. See Figure 14 for more information on switching waveforms.
- (2) These values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (3) Measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (4) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{ACL}$ ,  $t_{CPW}$ ,  $t_{EN}$ , and  $t_{SEXP}$  parameters for macrocells running in low-power mode.

Table 30. EPM7512B External Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-5		-7		-10		
			Min	Max	Min	Max	Min	Max	
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF (2)		5.5		7.5		10.0	ns
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF (2)		5.5		7.5		10.0	ns
t <sub>SU</sub>	Global clock setup time	(2)	3.6		4.9		6.5		ns
t <sub>H</sub>	Global clock hold time	(2)	0.0		0.0		0.0		ns
t <sub>FSU</sub>	Global clock setup time of fast input		1.0		1.5		1.5		ns
t <sub>FH</sub>	Global clock hold time of fast input		1.0		1.0		1.0		ns
t <sub>FZHSU</sub>	Global clock setup time of fast input with zero hold time		2.5		3.0		3.0		ns
t <sub>FZHH</sub>	Global clock hold time of fast input with zero hold time		0.0		0.0		0.0		ns
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF	1.0	3.7	1.0	5.0	1.0	6.7	ns
t <sub>CH</sub>	Global clock high time		3.0		3.0		4.0		ns
t <sub>CL</sub>	Global clock low time		3.0		3.0		4.0		ns
t <sub>ASU</sub>	Array clock setup time	(2)	1.4		1.9		2.5		ns
t <sub>AH</sub>	Array clock hold time	(2)	0.5		0.6		0.8		ns
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF (2)	1.0	5.9	1.0	8.0	1.0	10.7	ns
t <sub>ACH</sub>	Array clock high time		3.0		3.0		4.0		ns
t <sub>ACL</sub>	Array clock low time		3.0		3.0		4.0		ns
t <sub>CPPW</sub>	Minimum pulse width for clear and preset		3.0		3.0		4.0		ns
t <sub>CNT</sub>	Minimum global clock period	(2)		6.1		8.4		11.1	ns
f <sub>CNT</sub>	Maximum internal global clock frequency	(2), (3)	163.9		119.0		90.1		MHz
t <sub>ACNT</sub>	Minimum array clock period	(2)		6.1		8.4		11.1	ns
f <sub>ACNT</sub>	Maximum internal array clock frequency	(2), (3)	163.9		119.0		90.1		MHz

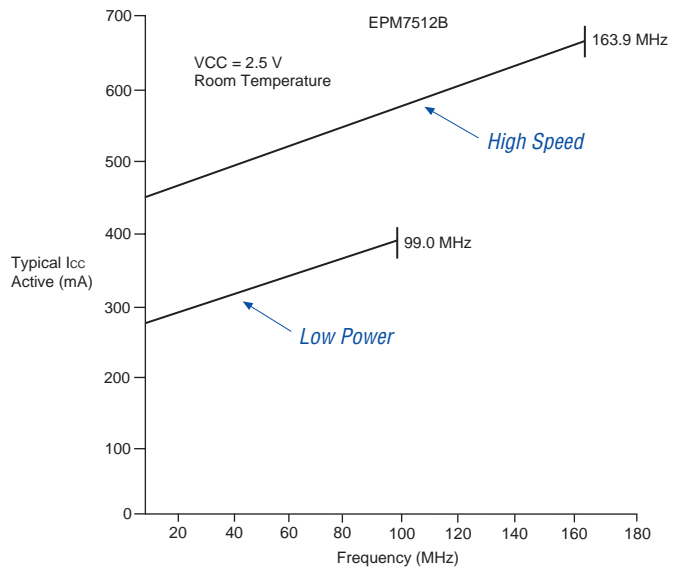
**Table 31. EPM7512B Internal Timing Parameters** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-5		-7		-10		
			Min	Max	Min	Max	Min	Max	
$t_{IN}$	Input pad and buffer delay			0.3		0.3		0.5	ns
$t_{IO}$	I/O input pad and buffer delay			0.3		0.3		0.5	ns
$t_{FIN}$	Fast input delay			2.2		3.2		4.0	ns
$t_{FIND}$	Programmable delay adder for fast input			1.5		1.5		1.5	ns
$t_{SEXP}$	Shared expander delay			1.5		2.1		2.7	ns
$t_{PEXP}$	Parallel expander delay			0.4		0.5		0.7	ns
$t_{LAD}$	Logic array delay			1.7		2.3		3.0	ns
$t_{LAC}$	Logic control array delay			1.5		2.0		2.6	ns
$t_{IOE}$	Internal output enable delay			0.1		0.2		0.2	ns
$t_{OD1}$	Output buffer and pad delay slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$		0.9		1.2		1.6	ns
$t_{OD3}$	Output buffer and pad delay slow slew rate = on $V_{CCIO} = 2.5\text{ V}$ or $3.3\text{ V}$	$C1 = 35\text{ pF}$		5.9		6.2		6.6	ns
$t_{ZX1}$	Output buffer enable delay slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$		2.8		3.8		5.0	ns
$t_{ZX3}$	Output buffer enable delay slow slew rate = on $V_{CCIO} = 2.5\text{ V}$ or $3.3\text{ V}$	$C1 = 35\text{ pF}$		7.8		8.8		10.0	ns
$t_{XZ}$	Output buffer disable delay	$C1 = 5\text{ pF}$		2.8		3.8		5.0	ns
$t_{SU}$	Register setup time		1.5		2.0		2.6		ns
$t_H$	Register hold time		0.4		0.5		0.7		ns
$t_{FSU}$	Register setup time of fast input		0.8		1.1		1.1		ns
$t_{FH}$	Register hold time of fast input		1.2		1.4		1.4		ns
$t_{RD}$	Register delay			0.5		0.7		1.0	ns
$t_{COMB}$	Combinatorial delay			0.2		0.3		0.4	ns
$t_{IC}$	Array clock delay			1.8		2.4		3.1	ns
$t_{EN}$	Register enable time			1.5		2.0		2.6	ns
$t_{GLOB}$	Global control delay			2.0		2.8		3.6	ns
$t_{PRE}$	Register preset time			1.0		1.4		1.9	ns
$t_{CLR}$	Register clear time			1.0		1.4		1.9	ns
$t_{PIA}$	PIA delay	(2)		2.4		3.4		4.5	ns
$t_{LPA}$	Low-power adder	(4)		2.0		2.7		3.6	ns



**Table 32. EPM7512B Selectable I/O Standard Timing Adder Delays (Part 1 of 2)** *Note (1)*

I/O Standard	Parameter	Speed Grade						Unit
		-5		-7		-10		
		Min	Max	Min	Max	Min	Max	
3.3 V TTL/CMOS	Input to PIA		0.0		0.0		0.0	ns
	Input to global clock and clear		0.0		0.0		0.0	ns
	Input to fast input register		0.0		0.0		0.0	ns
	All outputs		0.0		0.0		0.0	ns
2.5 V TTL/CMOS	Input to PIA		0.4		0.5		0.7	ns
	Input to global clock and clear		0.3		0.4		0.5	ns
	Input to fast input register		0.2		0.3		0.3	ns
	All outputs		0.2		0.3		0.3	ns
1.8 V TTL/CMOS	Input to PIA		0.7		1.0		1.3	ns
	Input to global clock and clear		0.6		0.8		1.0	ns
	Input to fast input register		0.5		0.6		0.8	ns
	All outputs		1.3		1.8		2.3	ns
SSTL-2 Class I	Input to PIA		1.5		2.0		2.7	ns
	Input to global clock and clear		1.4		1.9		2.5	ns
	Input to fast input register		1.1		1.5		2.0	ns
	All outputs		0.0		0.0		0.0	ns
SSTL-2 Class II	Input to PIA		1.5		2.0		2.7	ns
	Input to global clock and clear		1.4		1.9		2.5	ns
	Input to fast input register		1.1		1.5		2.0	ns
	All outputs		−0.1		−0.1		−0.2	ns
SSTL-3 Class I	Input to PIA		1.4		1.9		2.5	ns
	Input to global clock and clear		1.2		1.6		2.2	ns
	Input to fast input register		1.0		1.4		1.8	ns
	All outputs		0.0		0.0		0.0	ns
SSTL-3 Class II	Input to PIA		1.4		1.9		2.5	ns
	Input to global clock and clear		1.2		1.6		2.2	ns
	Input to fast input register		1.0		1.4		1.8	ns
	All outputs		0.0		0.0		0.0	ns
GTL+	Input to PIA		1.8		2.5		3.3	ns
	Input to global clock and clear		1.9		2.6		3.5	ns
	Input to fast input register		1.8		2.5		3.3	ns
	All outputs		0.0		0.0		0.0	ns

**Figure 19.  $I_{CC}$  vs. Frequency for EPM7512B Devices**

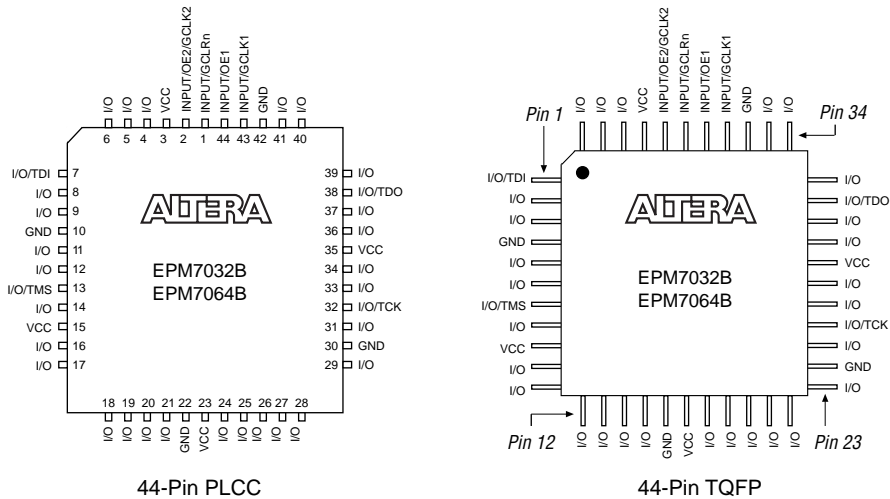
## Device Pin-Outs

See the Altera web site (<http://www.altera.com>) or the *Altera Digital Library* for pin-out information.

Figures 20 through 29 show the package pin-out diagrams for MAX 7000B devices.

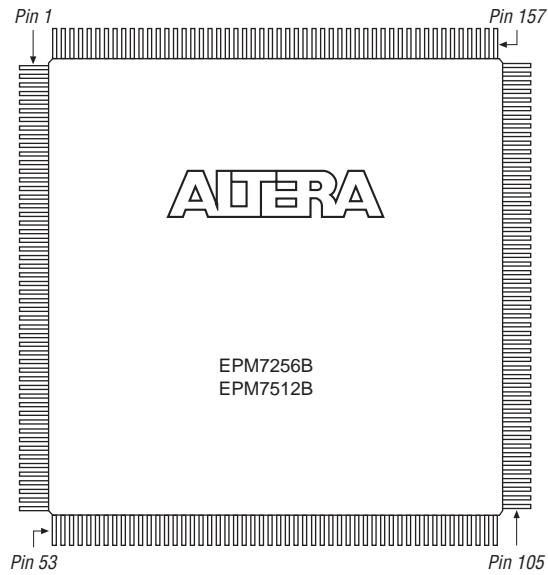
**Figure 20. 44-Pin PLCC/TQFP Package Pin-Out Diagram**

*Package outlines not drawn to scale.*



**Figure 27. 208-Pin PQFP Package Pin-Out Diagram**

*Package outline not drawn to scale.*



### Version 3.3

The following changes were made to the *MAX 7000B Programmable Logic Device Family Data Sheet* version 3.3:

- Updated [Table 3](#).
- Added [Tables 4](#) through [6](#).

### Version 3.2

The following changes were made to the *MAX 7000B Programmable Logic Device Family Data Sheet* version 3.2:

- Updated [Note \(10\)](#) and added ambient temperature ( $T_A$ ) information to [Table 15](#).

### Version 3.1

The following changes were made to the *MAX 7000B Programmable Logic Device Family Data Sheet* version 3.1:

- Updated  $V_{IH}$  and  $V_{IL}$  specifications in [Table 16](#).
- Updated leakage current conditions in [Table 16](#).

### Version 3.0

The following changes were made to the *MAX 7000B Programmable Logic Device Family Data Sheet* version 3.0:

- Updated timing numbers in [Table 1](#).
- Updated [Table 16](#).
- Updated timing in [Tables 18, 19, 21, 22, 24, 25, 27, 28, 30, and 31](#).



101 Innovation Drive  
San Jose, CA 95134  
(408) 544-7000  
<http://www.altera.com>  
[Applications Hotline:](#)  
(800) 800-EPLD  
[Customer Marketing:](#)  
(408) 544-7104  
[Literature Services:](#)  
[lit\\_req@altera.com](mailto:lit_req@altera.com)

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